

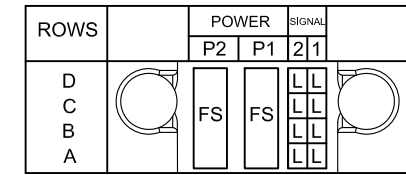
REV.	SPECIFICATION	ECN NO.	APPD.
R1		ECN200320	

**Material and Plating:**  
**Housing:** LCP, UL94V-0, BLACK.  
**Power Contacts:** High Conductivity Copper.  
 30u"Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Press Fit over nickel 50u" Min .  
**Signal Contact:** Phosphor Bronze.  
 30u"Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Press Fit over nickel 50u" Min .

**Electrical Characteristics:**  
**Current Rating:** Signal Pin 2.5 AMP.  
 Power Pin 30 AMP.  
**Dielectric Withstanding Voltage:**  
 Signal Pin DC 1000V For 1 minute.  
 Power Pin DC 2500V For 1 minute.  
**Insulator Resistance:** Signal Pin 5000MΩ min. at DC 500V.  
 Power Pin 20000MΩ min. at DC 500V.  
**Contact Resistance:** Signal Pin 15mΩ max. at DC 20mA.  
 Power Pin 0.7mΩ max. at DC 20mA.  
**Operating Temperature:** -40°C ~+105°C .

**\*RoHS Compliant**

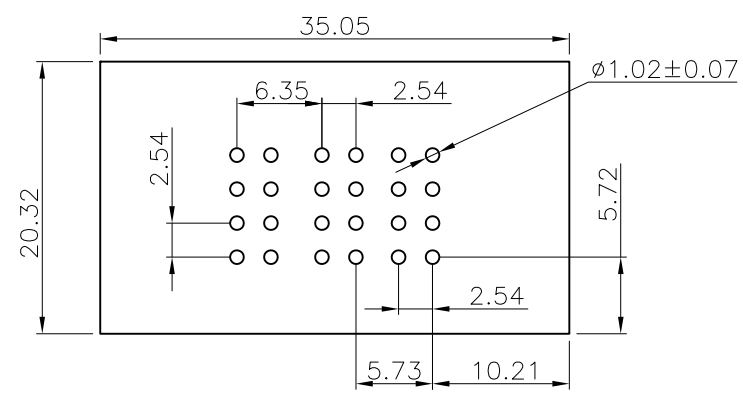
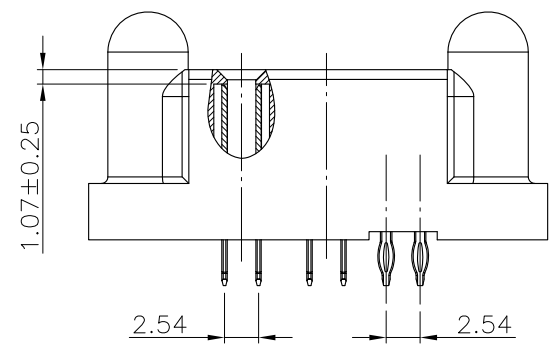
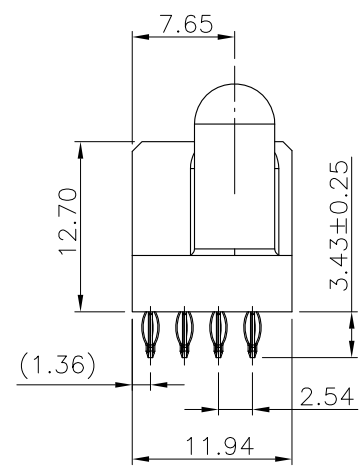
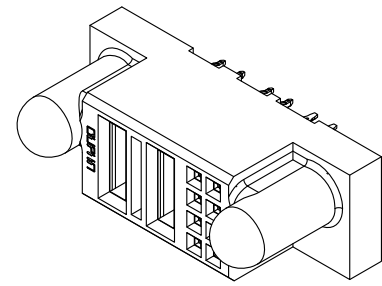
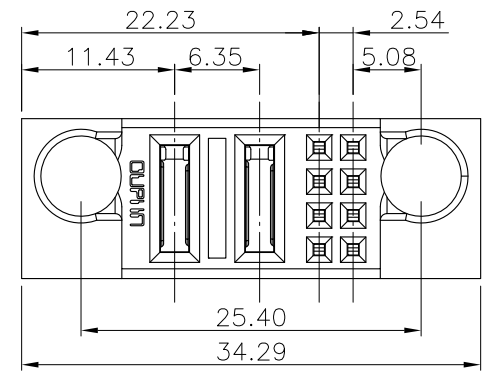
Notes :  
 H: High density Power---PCB Mount 5.08mm Pitch  
 P: DC Power---PCB Mount 6.35mm Pitch  
 A: AC Power---PCB Mount 7.62mm Pitch  
 S: Signal---PCB Mount 2.54mm Pitch



POWER CONTACT TO THE TOP DISTANCE 2.34mm, THE MATING LENGTH 3.87mm	FM
POWER CONTACT TO THE TOP DISTANCE 1.07mm, THE MATING LENGTH 5.14mm	FS
SIGNAL CONTACT 3.43 SOLDER TAIL, PD/NI	L

9391-A 2 P02 S08 CB 30 P A

Series ——— A: Tray Package  
 2: Female Straight ——— P: Press Fit Type  
 Power Contact: Hxx, Pxx, Axx ——— 30: 30u"  
 No. of Position ——— CB: Dip Tin Plated  
 Signal Contact: Sxx ——— Contact Au+Pd/Ni Plated  
 No. of Position



P.C.Board Layout  
 (Tolerance: ±0.05)

Tolerances	Dwg No.	9391-D0000-252	Title:
x. = ±0.50	Projection		9391-A Series
.x = ±0.25	Unit	mm	Female Straight
.xx = ±0.15	Scale	1:1	Press Fit Type
	Drawn By	bo-min 09/09'19	

**OUPIN**  
 OUPIN ELECTRONIC(KUNSHAN) CO., LTD.  
 P/N: 9391-A2P02S08CB30PA

SHEET	1/1	Ver.No.	R1
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